

Remarks

This is intended as a full and complete response to the Office Action dated August 30, 2006, having a shortened statutory period for response extended to January 30, 2006. Please reconsider the claims pending in the application for the reasons discussed below.

Claims 23-27 and 40-47 remain pending in the application and are shown above. Claims 23-27 stand rejected by the Examiner. Reconsideration of the rejected claims is requested for the reasons presented below.

Claim 23 is amended to clarify the invention. Claim 23 is amended to recite monitoring a thickness of a surface film on the substrate, the monitoring comprising reflecting a beam from the surface film; and adjusting the flowing of polishing fluid to the first portion and the second portion based upon the monitoring. New claims 40-47 are added. These amendments are not presented to distinguish a reference, thus, the claims as amended are entitled to a full range of equivalents if not previously amended to distinguish a reference. Support for the amendments and new claims may be found at least at paragraphs [0032] – [0035] and Figure 1.

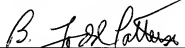
Claims 23-27 are rejected under 35 U.S.C. § 102(e) as being anticipated by U.S. Patent No. 6,336,850 to *Wada et al.* Applicants respectfully traverse the rejection.

Wada et al. does not disclose a method of supplying a polishing fluid to a chemical mechanical polishing surface comprising monitoring a thickness of a surface film on the substrate wherein the monitoring comprises reflecting a beam from the surface film and adjusting the flow of polishing fluid to the first portion and the second portion based upon the monitoring. *Wada et al.* is silent regarding monitoring by reflecting a beam. Therefore, *Wada et al.*, alone or in combination, does not teach, show, or suggest a method of supplying a polishing fluid to a chemical mechanical polishing surface comprising monitoring a thickness of a surface film on the substrate wherein the monitoring comprises reflecting a beam from the surface film and adjusting the flow of polishing fluid to the first portion and the second portion based upon the monitoring, as recited in claim 23, and claims dependent thereon. Withdrawal of the rejection is respectfully requested.

In conclusion, the references cited by the Examiner, alone or in combination, do not teach, show, or suggest the invention as claimed.

Having addressed all issues set out in the office action, Applicants respectfully submit that the claims are in condition for allowance and respectfully request that the claims be allowed.

Respectfully submitted,



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